

Soldered RSAM data sheet RSAM-λ-25.4s

GaAs chip area standard: 4mm x 4mm

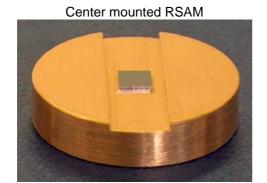
> optional: other dimensions on request

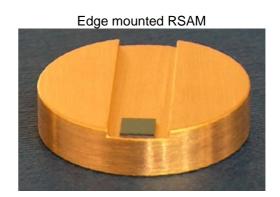
Chip thickness 400 µm standard:

Front side the RSAM is covered by a dielectric front mirror.

The RSAM chip is soldered on a gold plated Cu-cylinder with 25.4 mm Ø using a Pb/Sn solder. The solder provides a low thermal resistance between the RSAM and the mount.

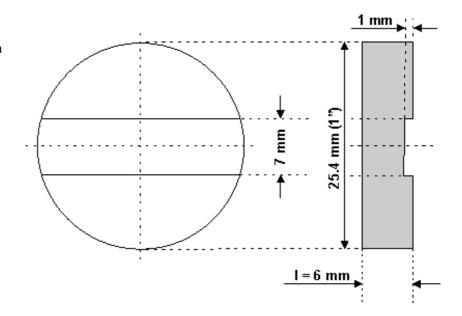
- The standard position of the RSAM is at the center of the mount.
- Optional the RSAM can be mounted at the edge of the mount without extra charges.





Mount

Cu-cylinder, $\emptyset = 25.4 \text{ mm}$ I = 6.0 mm



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